

MOS FET FJ6K01010L

FJ6K01010L Silicon P-channel MOS FET

For switching

Features

- Low drain-source On-state resistance : RDS (on) typ. = 26 m Ω (VGS = -4.5 V)
- Low drive voltage : 1.8 V drive
- Halogen-free / RoHS compliant
- (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter

Marking Symbol : T4

Drain-source voltage

Gate-source voltage

Pulse drain current

Total power dissipation

Operating ambient temperature

Channel temperature

Storage temperature

Drain current

Revised

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Note) *1 Measuring on Glass epoxy board (25.4 x 25.4 x 0.8 mm) (See Figure 1) Absolute maximum rating without heat sink for PD is 150 mW

Symbol

VDS

VGS

ID

IDp

PD

Tch

Topr

Tstg

Rating

-12

±8

-4.0

-20

700

150

-40 to + 85

-55 to +150

Unit

V

V

А

А

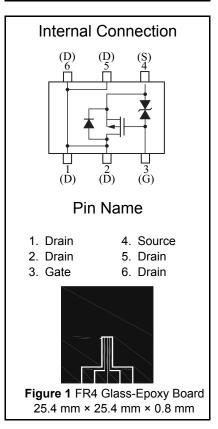
mW

°C

°C

°C

| | Unit : mm | | | | |
|---------------------------------|-----------------------------------|--|--|--|--|
| | | | | | |
| 1. Drain 2. Drain 3. Gate | 4. Source 5. Drain 6. Drain | | | | |
| Panasonic | WSMini6-F1-B | | | | |
| JEITA | SC-113DA | | | | |
| Code | _ | | | | |



Established : 2010-04-05 : 2013-07-01



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| Electrical Characteristics | Ta = 25 °C ± 3 °C |
|----------------------------|-------------------|
|----------------------------|-------------------|

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|-----------------------------------|----------|---------------------------------|------|-------|------|------|
| Drain-source breakdown voltage | VDSS | ID = -1 mA, VGS = 0 | -12 | | | V |
| Drain-source cutoff current | IDSS | VDS = -10 V, VGS = 0 | | | -1.0 | μA |
| Gate-source cutoff current | IGSS | VGS = ±8 V, VDS = 0 | | | ±10 | μA |
| Gate threshold voltage | Vth | ID = -1.0 mA, VDS = -6.0 V | -0.3 | -0.65 | -1.0 | V |
| | RDS(on)1 | -) | | 26 | 34 | |
| Drain-source ON resistance | RDS(on)2 | ID = -0.5 A, VGS = -2.5 V | | 30 | 41 | mΩ |
| | RDS(on)3 | ID = -0.5 A, VGS = -1.8 V | | 36 | 54 | I |
| Forward transfer admittance | Yfs | ID = -1.0 A, VDS = -10 V | 4.0 | | | S |
| Input capacitance | Ciss | VDS = -10 V, VGS = 0, f = 1 MHz | | 1 400 | | pF |
| Output capacitance | Coss | | | 190 | | pF |
| Reverse transfer capacitance | Crss | | | 210 | | pF |
| Turn-on delay time ^{*1} | td(on) | VDD = -6 V, VGS = 0 to -4 V | | 9 | | ns |
| Rise time *1 | tr | ID = -1.0 A | | 40 | | ns |
| Turn-off delay time ^{*1} | td(off) | VDD = -6 V, VGS = -4 to 0 V | | 250 | | ns |
| Fall time ^{*1} | tf | ID = -1.0 A | | 150 | | ns |

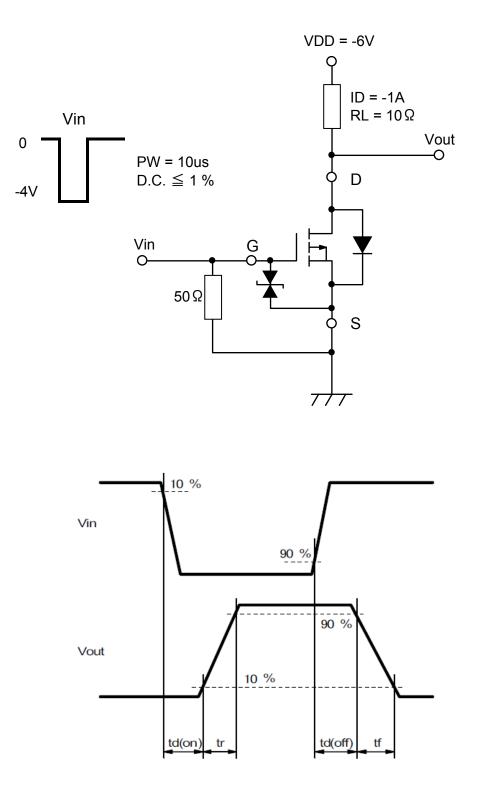
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. *1 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time

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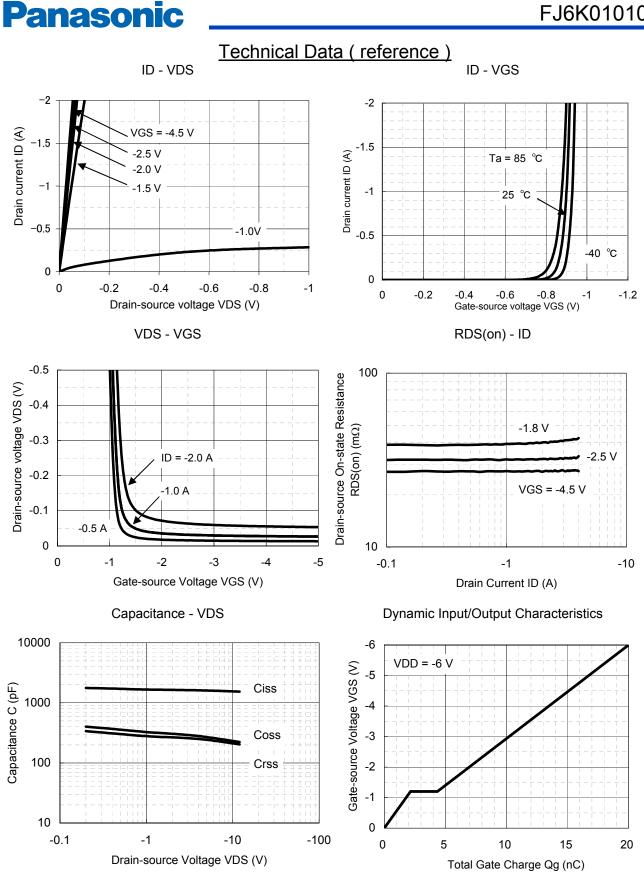


*1 Measurement circuit for Turn-on Delay Time/Rise Time/Turn-off Delay Time/Fall Time



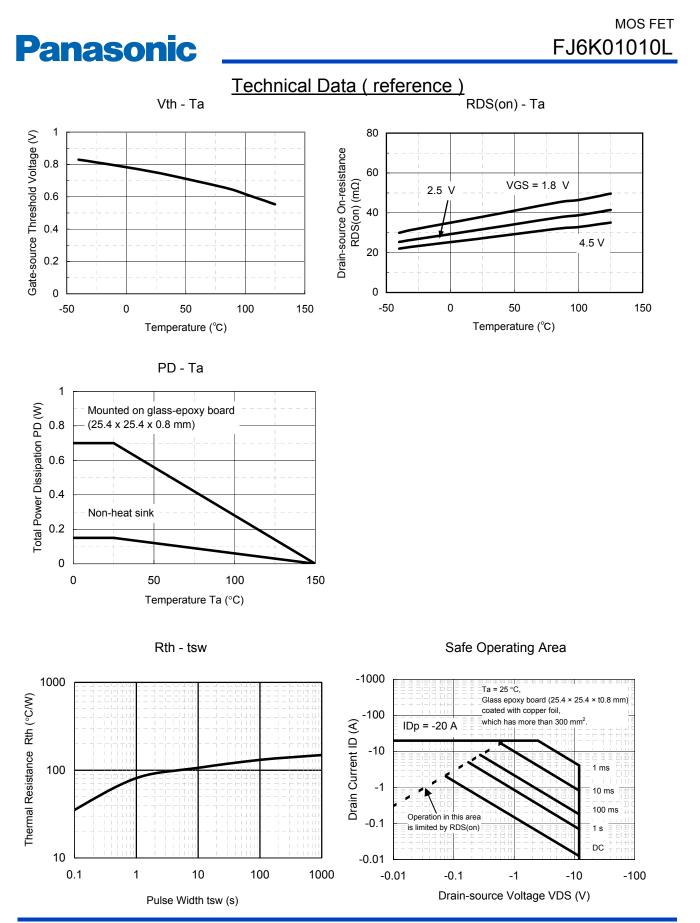
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MOS FET FJ6K01010L



Page 4 of 6

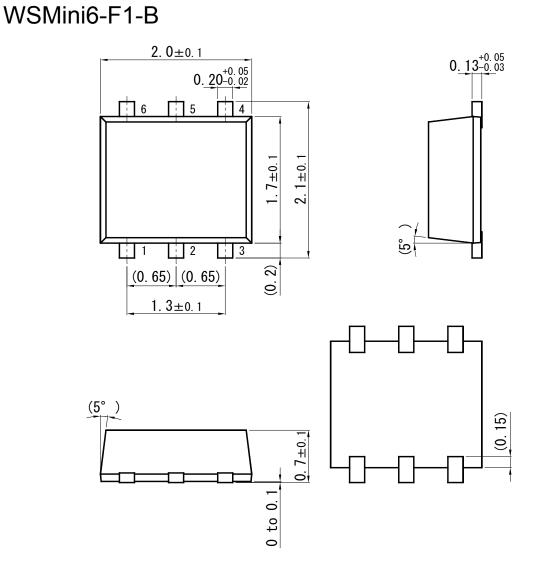




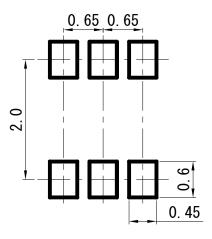
Page 5 of 6



MOS FET FJ6K01010L



Land Pattern (Reference) (Unit : mm)



Unit : mm

Page 6 of 6

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